

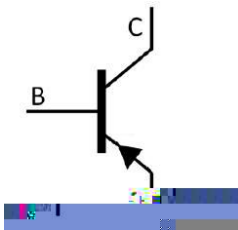
/ Descriptions

JF K\$) * GE G` Silicon PNP transistor in a SOT-23 Plastic Package.

/ Features

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Low saturation voltage, excellent h_{FE} linearity and high h_{FE} .

Output stage of audio amplifier, voltage regulator, DC-DC converter and relay driver.



PIN1 Base PIN 2 Emitter PIN 3 Collector

/ h_{FE} Classifications & Marking

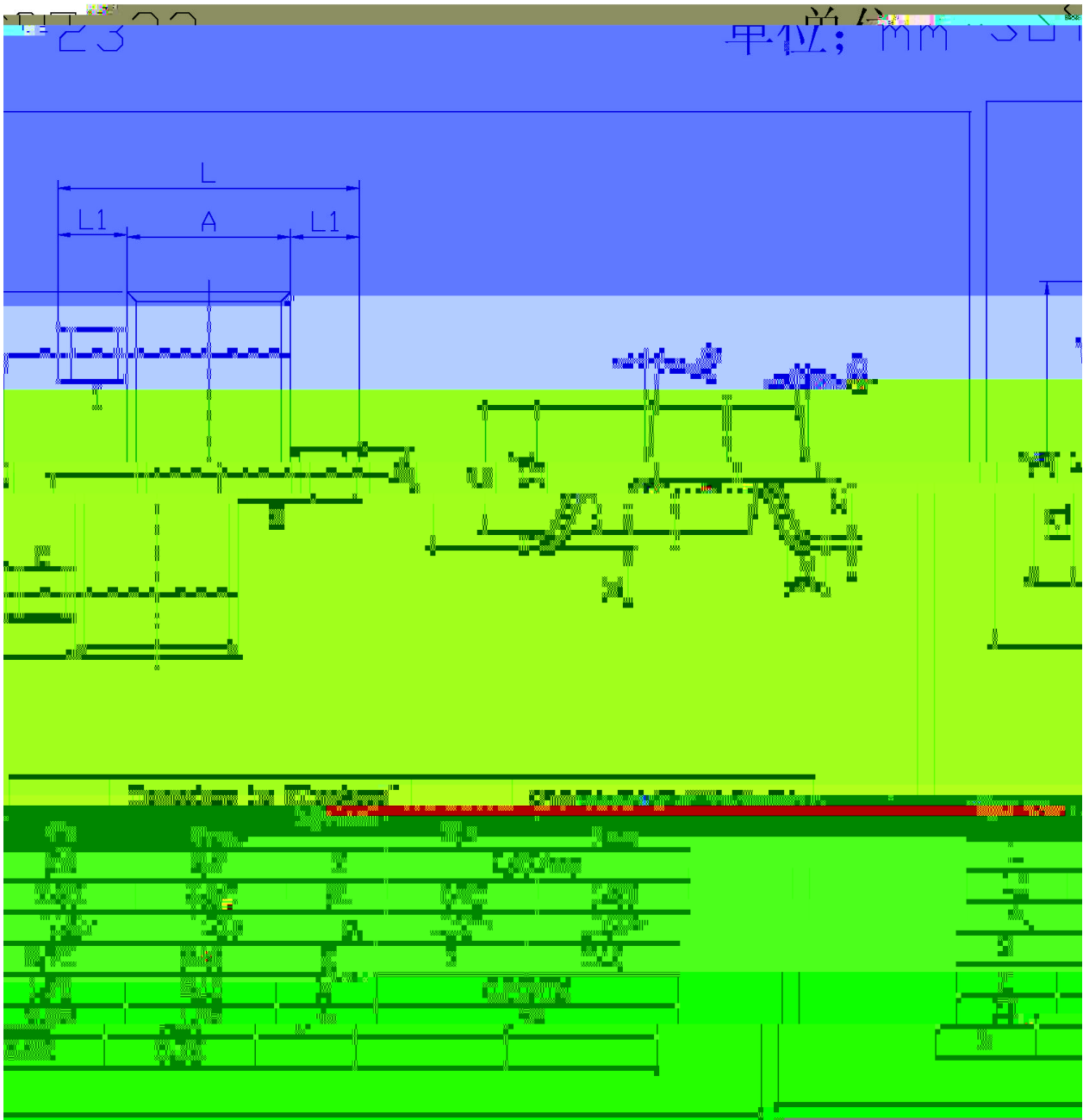
Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-40	V
Collector to Emitter Voltage	V_{CEO}	-30	V
Emitter to Base Voltage	V_{EBO}	-5	V
Collector Current - DC	I_C	-3	A
Collector Current - Pulse	I_{CP}	-7	A
Collector Power Dissipation	P_C	350	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	V_{CBO}	$I_C=-100\mu A$ $I_E=0$	-40			V
Collector to Emitter Breakdown Voltage	V_{CEO}	$I_C=-1.0mA$ $I_B=0$	-30			V
Emitter to Base Breakdown Voltage	V_{EBO}	$I_E=-100\mu A$ $I_C=0$	-5			V

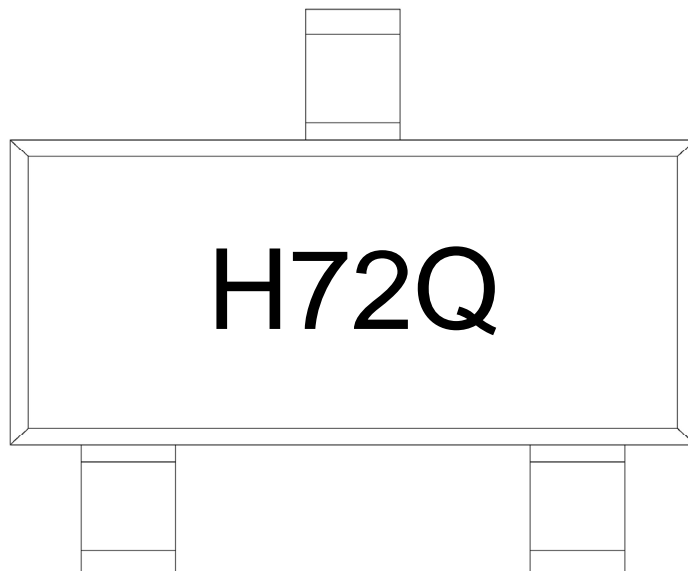
2SB772M
Rev.F Apr.-2017

DATA SHEET

/ Package Dimensions



/ Marking Instructions

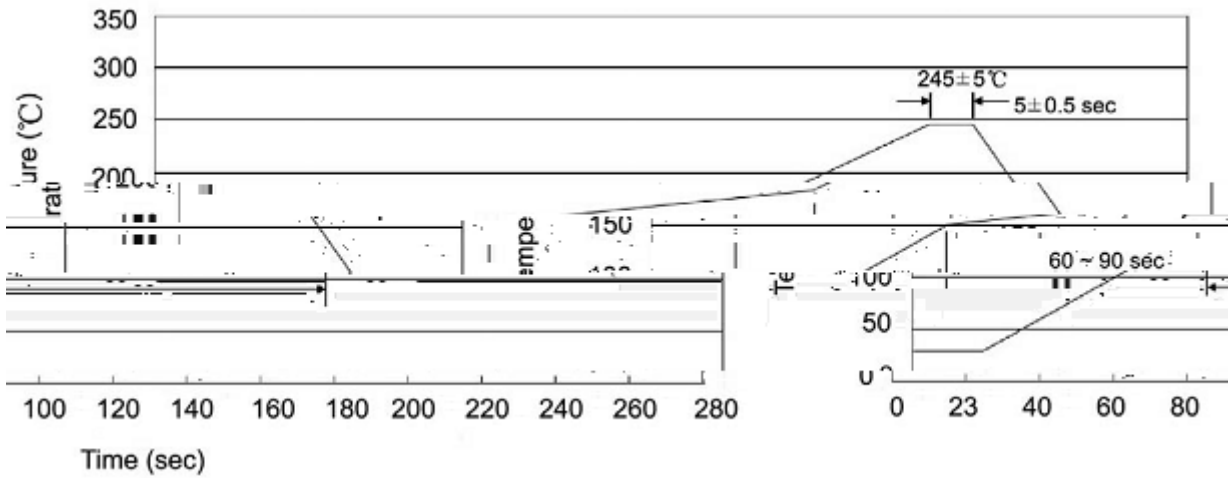


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Note:

- H: Company Code
- 72: Product Type Code
- Q: h_{FE} Classifications Symbol Code

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-------|----------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 245±5 | | 5±0.5 | sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		

/ Notices